REGULATORY COMPLIANCE

Lead Free Pb COMPLIANT

EU RoHS 2011/65 + 2015/863 COMPLIANT

China RoHS COMPLIANT

REACH SVHC COMPLIANT

DRC CONFLICT FREE

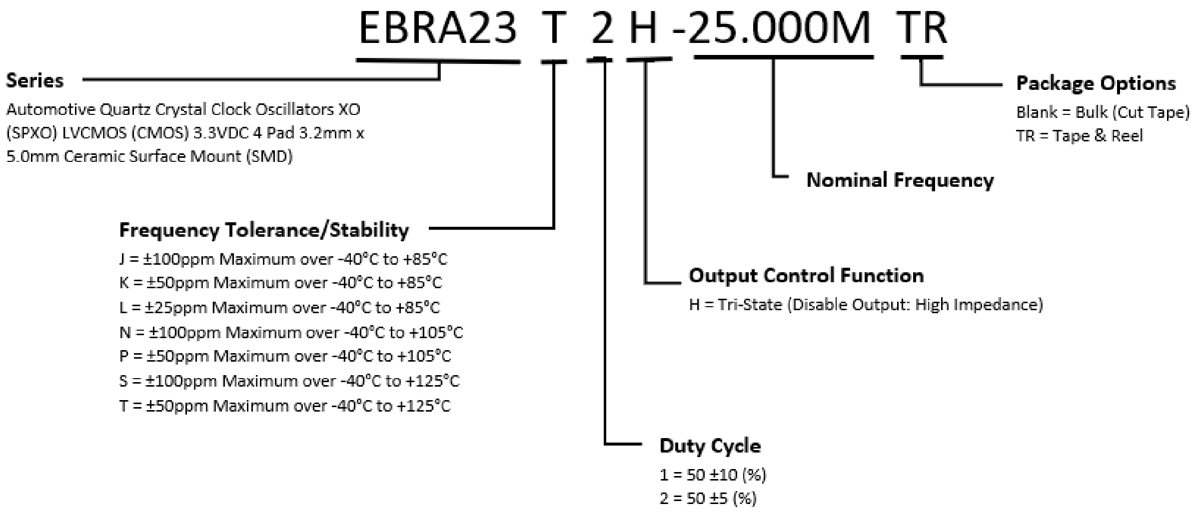
ITEM DESCRIPTION

Automotive Grade Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 4 Pad 3.2mm x 5.0mm Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICATIONS

Nominal Frequency	1.000MHz to 156.250MHz
Frequency Tolerance/Stability	Inclusive of all conditions: Calibration Tolerance (at 25°C), Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, and First Year Aging at 25°C ±100ppm Maximum over -40°C to +85°C ±50ppm Maximum over -40°C to +85°C ±25ppm Maximum over -40°C to +85°C ±100ppm Maximum over -40°C to +105°C ±50ppm Maximum over -40°C to +105°C ±100ppm Maximum over -40°C to +125°C ±50ppm Maximum over -40°C to +125°C
Aging at 25°C	±3ppm/year Maximum
Supply Voltage	3.3Vdc ±10%
Input Current	Unloaded 10mA Maximum (1 to 60MHz) 25mA Maximum (60.001 to 156.250MHz)
Output Voltage Logic High (Voh)	IOH = -4mA 90% of Vdd Minimum
Output Voltage Logic Low (Vol)	IOL = +4mA 10% of Vdd Maximum
Rise/Fall Time	Measured at 20% to 80% of Waveform 6nSec Maximum
Duty Cycle	Measured at 50% of Waveform 50 ±10(%) 50 ±5(%)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Output Control Input Voltage Logic High (Vih)	70% of Vdd Minimum or No Connect to Enable Output
Output Control Input Voltage Logic Low (Vil)	30% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	Without Load 10µA Maximum
Period Jitter (RMS)	5pSec Maximum
Period Jitter (pk-pk)	30pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

PART NUMBERING GUIDE



EBRA23 T 2 H -25.000M TR

Series

Automotive Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3VDC 4 Pad 3.2mm x 5.0mm Ceramic Surface Mount (SMD)

Frequency Tolerance/Stability

J = ±100ppm Maximum over -40°C to +85°C
K = ±50ppm Maximum over -40°C to +85°C
L = ±25ppm Maximum over -40°C to +85°C
N = ±100ppm Maximum over -40°C to +105°C
P = ±50ppm Maximum over -40°C to +105°C
S = ±100ppm Maximum over -40°C to +125°C
T = ±50ppm Maximum over -40°C to +125°C

Duty Cycle

1 = 50 ±10 (%)
2 = 50 ±5 (%)

Output Control Function

H = Tri-State (Disable Output: High Impedance)

Nominal Frequency

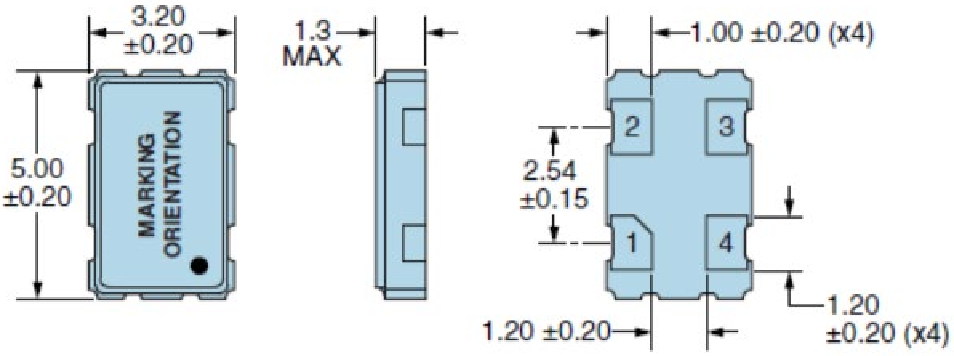
Package Options

Blank = Bulk (Cut Tape)
TR = Tape & Reel

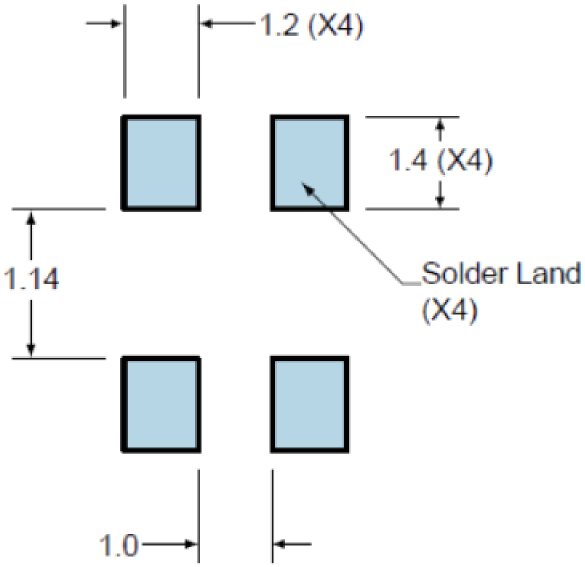
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

MECHANICAL DIMENSIONS



SUGGESTED SOLDER PAD LAYOUT

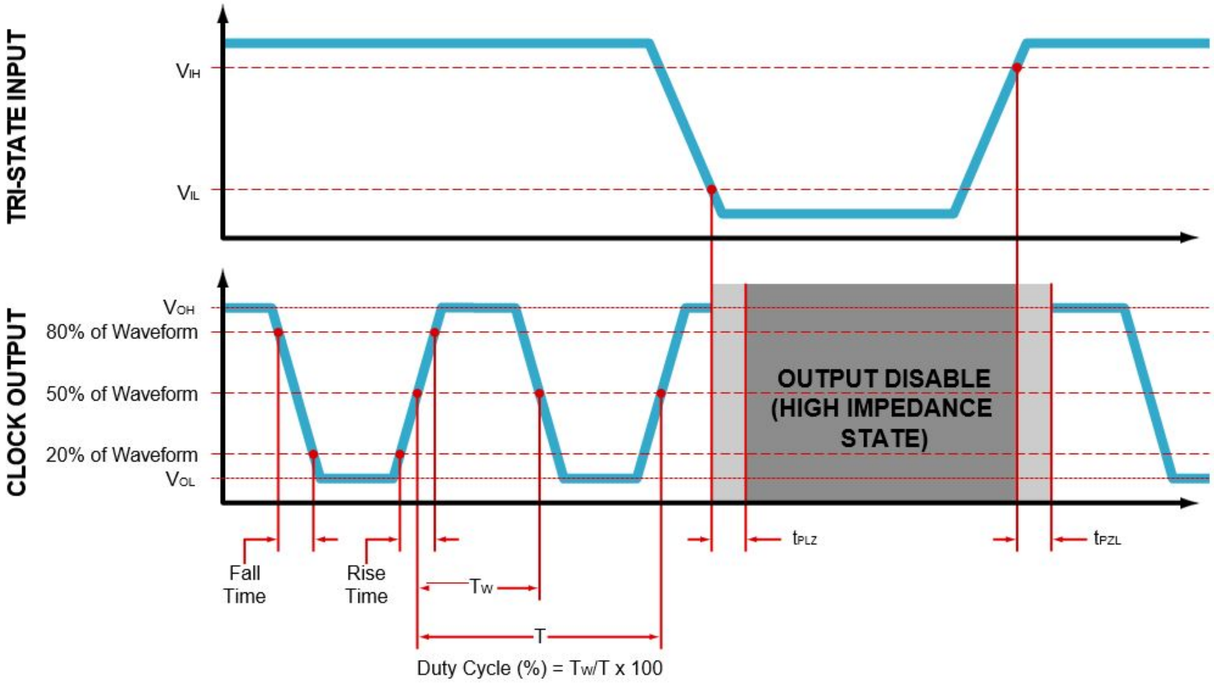


PIN	CONNECTION
1	Tri-State
2	Case/Ground
3	Output
4	Supply Voltage

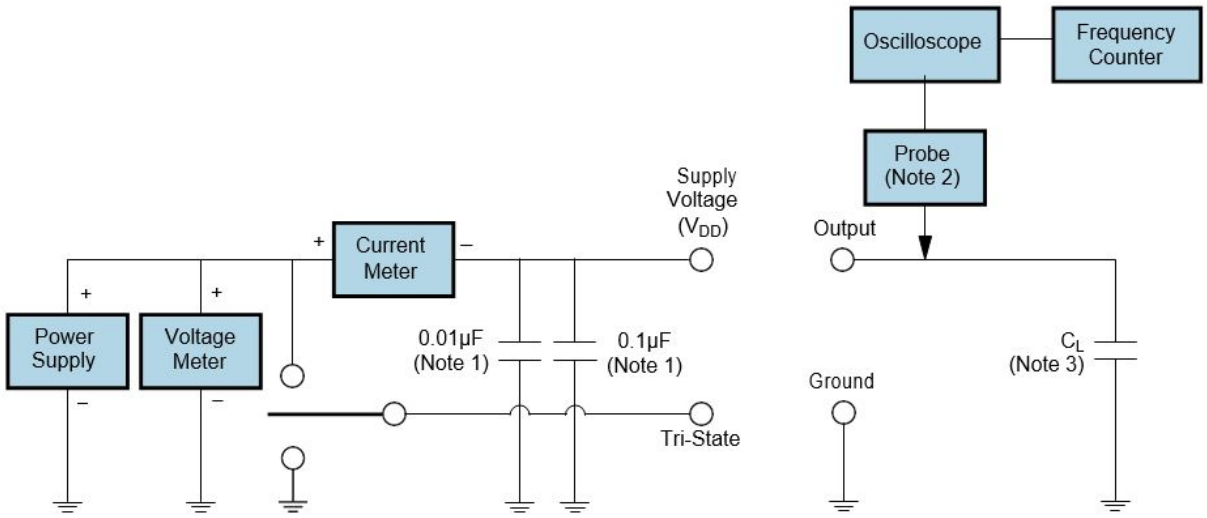
All Tolerances are ±0.1

All Dimensions in Millimeters

OUTPUT WAVEFORM & TIMING DIAGRAM



TEST CIRCUIT FOR CMOS OUTPUT



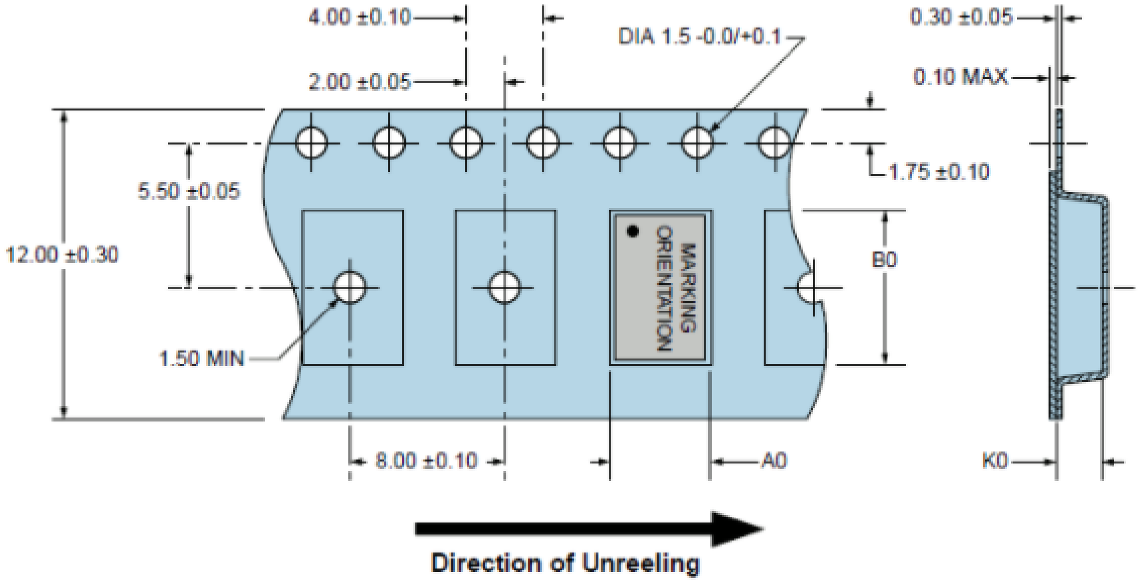
Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less Than 2mm) to the package ground and supply voltage pin is required.
Note 2: A low capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) Passive probe is recommended.
Note 3: Capacitance value CL includes sum of all probe and fixture capacitance.

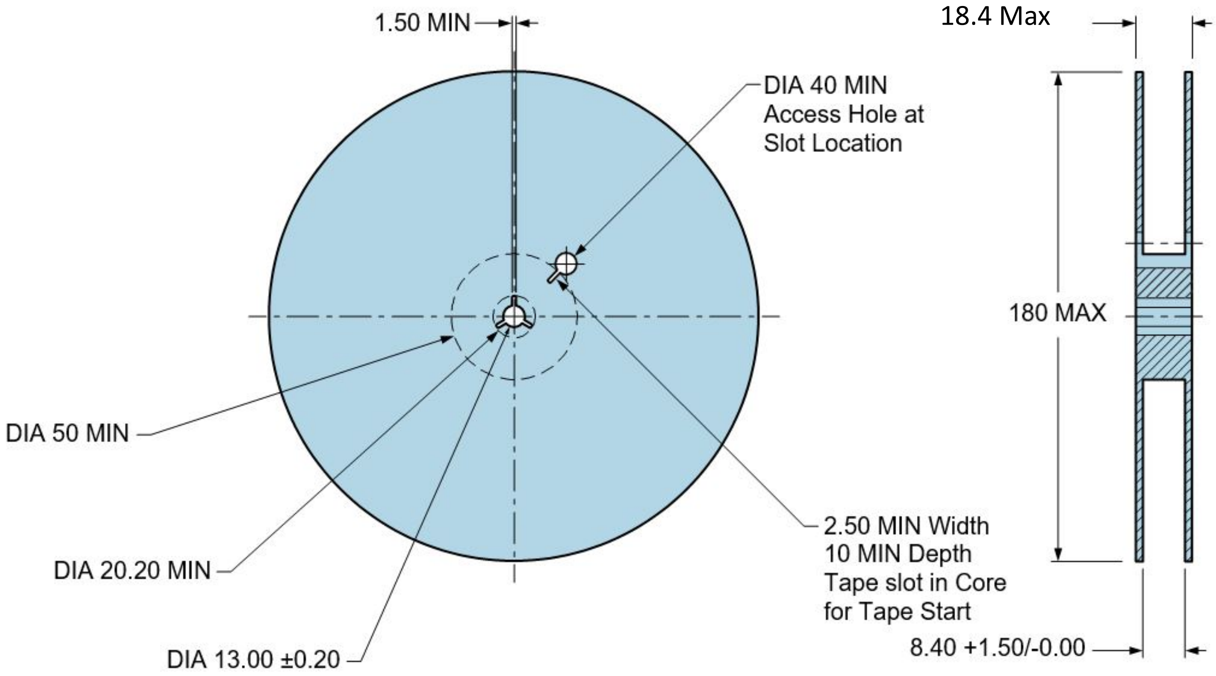
TAPE & REEL DIMENSIONS

Quantity per Reel: 3,000 Units

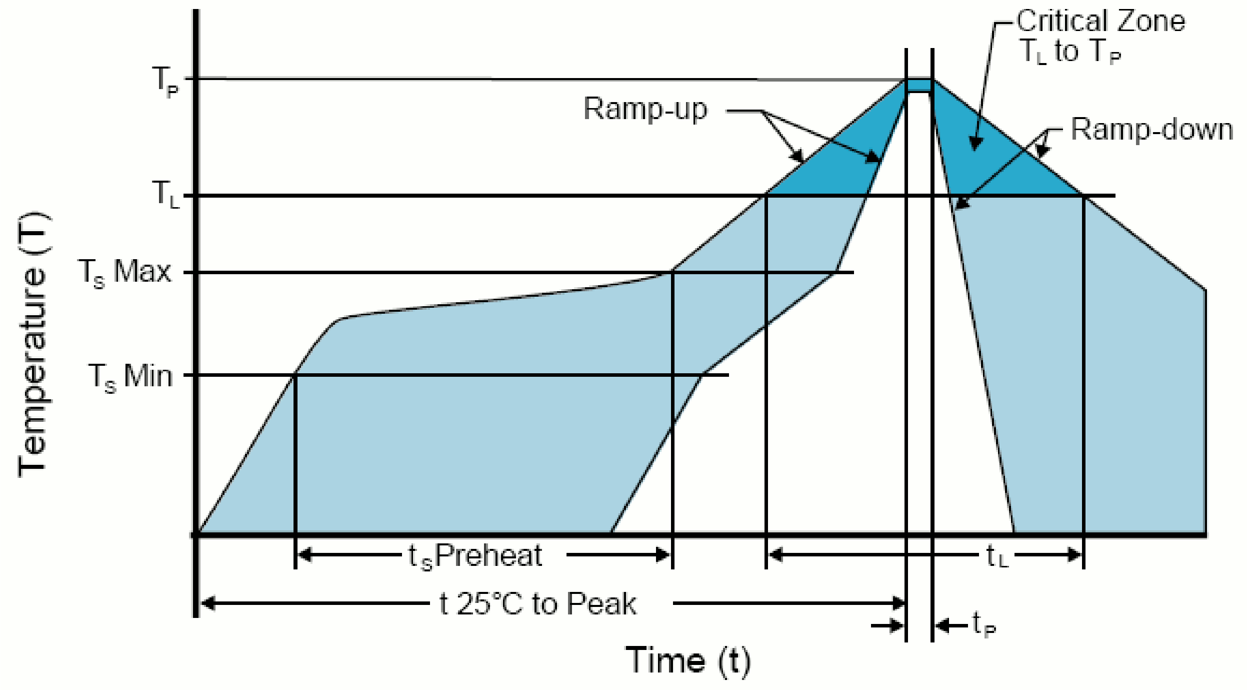
All Dimensions in Millimeters

Compliant to EIA-481





RECOMMENDED SOLDER REFLOW METHOD

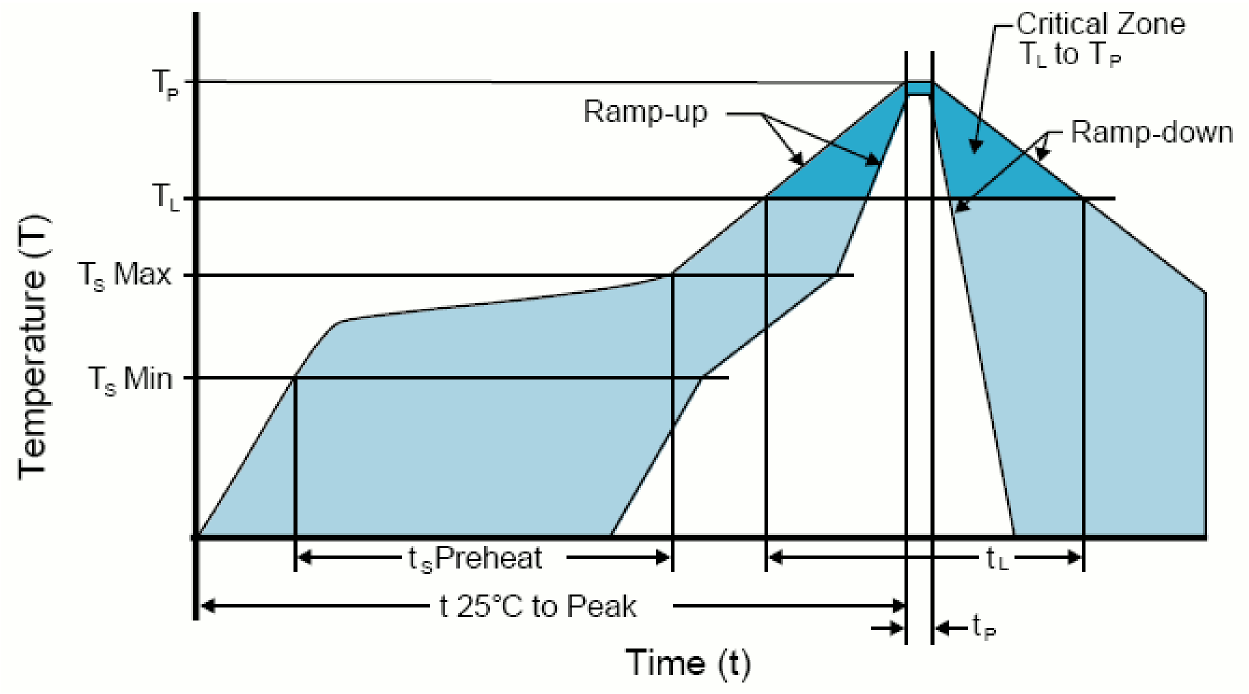


HIGH TEMPERATURE INFRARED/CONVECTION	
T_S MAX to T_L (Ramp-up Rate)	3°C/Second Maximum
Preheat **- Temperature Minimum (T_S MIN)** **- Temperature Typical (T_S TYP)** **- Temperature Maximum(T_S MAX)** **- Time (t_s MIN)**	 150°C 175°C 200°C 60 - 180 Seconds
Ramp-up Rate (T_L to T_P)	3°C/Second Maximum
Time Maintained Above: **- Temperature (T_L)** **- Time (t_L)**	 217°C 60 - 150 Seconds
Peak Temperature (T_P)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature(T_P Target)	250°C +0/-5°C
Time within 5°C of actual peak (t_p)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION	
T_S MAX to T_L (Ramp-up Rate)	5°C/Second Maximum
Preheat **- Temperature Minimum (T_S MIN)** **- Temperature Typical (T_S TYP)** **- Temperature Maximum(T_S MAX)** **- Time (t_S MIN)**	N/A 150°C N/A 60 - 120 Seconds
Ramp-up Rate (T_L to T_P)	5°C/Second Maximum
Time Maintained Above: **- Temperature (T_L)** **- Time (t_L)**	150°C 200 Seconds Maximum
Peak Temperature (T_P)	240°C Maximum
Target Peak Temperature(T_P Target)	240°C Maximum 2 Times/230˚C Maximum 1Time
Time within 5°C of actual peak (t_P)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)